

FIG. 1 (RELATED ART)

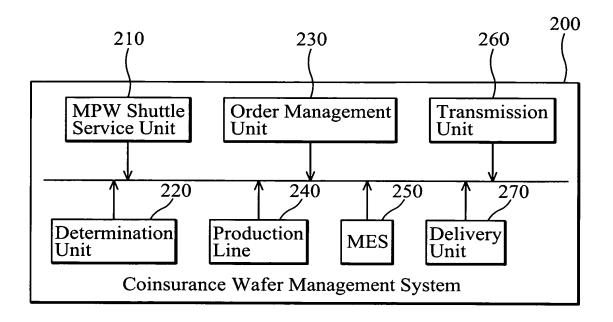
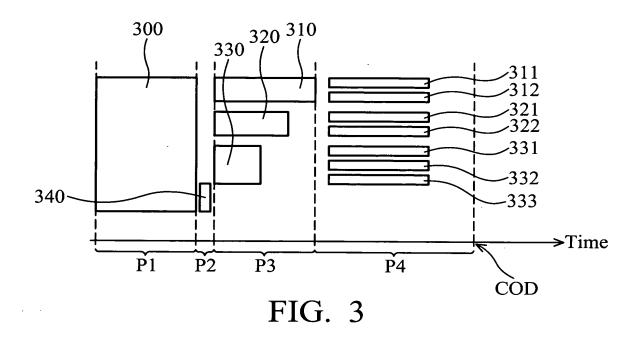


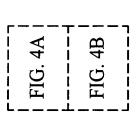
FIG. 2



400

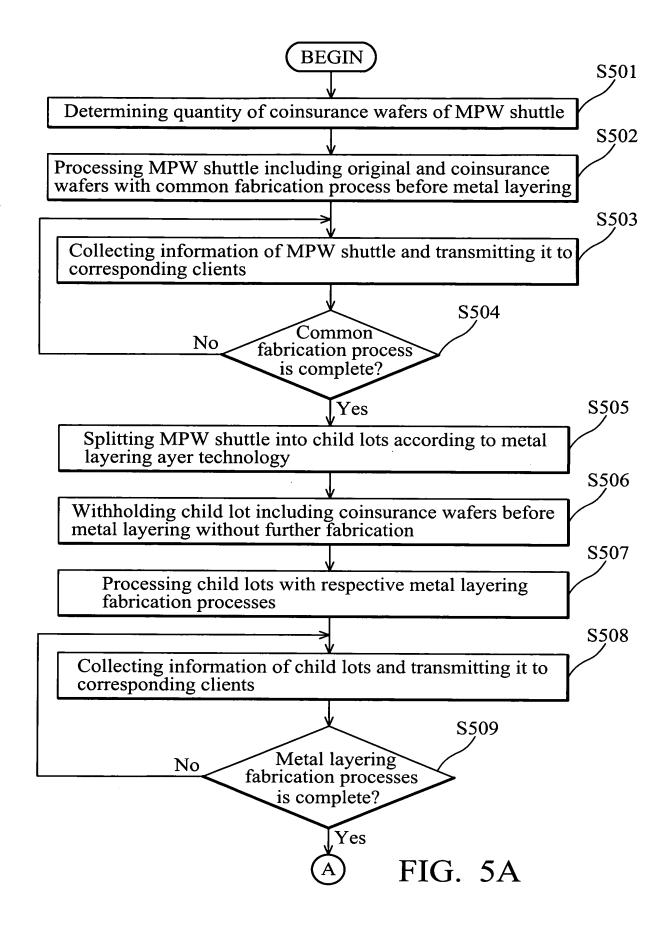
						_	
	Customer Code	Device Name	Lot ID	Wafer ID	Technology	Fab	Technology Fab Tape-in Date
	A023	TMB934_C15	D62600	TMB934_C15 D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	4A 6/5/2001
10	A458	TMB934_C11	D62600	TMB934_C11   D62600   05;06;07;08;09;10;11;12;13;14	0.18	4A	4A 6/5/2001
Ī	E288	TMB934_C3	D62600 03;04	03;04	0.18	4A	4A 6/5/2001
_	1181	TMB934_C5	D62600	D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	6/5/2001
	£9£Ñ	TMB934_C7	D62600	D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	4A 6/5/2001
	N376	TMB934_C4	D62600 03;04	03;04	0.18	4A	4A 6/5/2001
	U446	TMB934_C8	D62600 01;02	01;02	0.18	4A	4A 6/5/2001
	U583	TMB934_C9	D62600	D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	4A 6/5/2001
	90LN	TMB934_C2	D62600	D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	6/5/2001
	U759	TMB934_C6	D62600	D62600 05;06;07;08;09;10;11;12;13;14	0.18	4A	4A 6/5/2001
	U800	TMB934_C12 D62600 03;04	D62600	03;04	0.18	4A	4A 6/5/2001

FIG. 4*≱* 



Pr	ocess	#b#M	Process #P#M User Type	Committed Date	Committed Coinsurance Date Wafer ID
	MiM	MiM   1P6M+	Customer	9/5/2001	15;16
	MiM	MiM   1P6M+	Customer	9/5/2001	15;16
	MiM	1P6M+	MiM   1P6M+   Customer	9/10/2002	15;16
	MiM	MiM 1P6M+	Customer	1007/5/6	15;16
	MiM	1P6M+	Customer	9/2/2004	15;16
	MiM	MiM   1P6M+	Customer	6/10/2002	15;16
	MiM	1P6M+	MiM   1P6M+   Customer	9/15/2002	15;16
_	MiM	1P6M+	MiM   1P6M+   Customer	9/5/2007	15;16
	MiM	1P6M+	MiM   1P6M+   Customer	6/2/2007	15;16
	MiM	1P6M+	Customer	6/2/2007	15;16
	MiM	1P6M+	MiM   1P6M+   Customer	9/10/2002	15;16

FIG. 4B



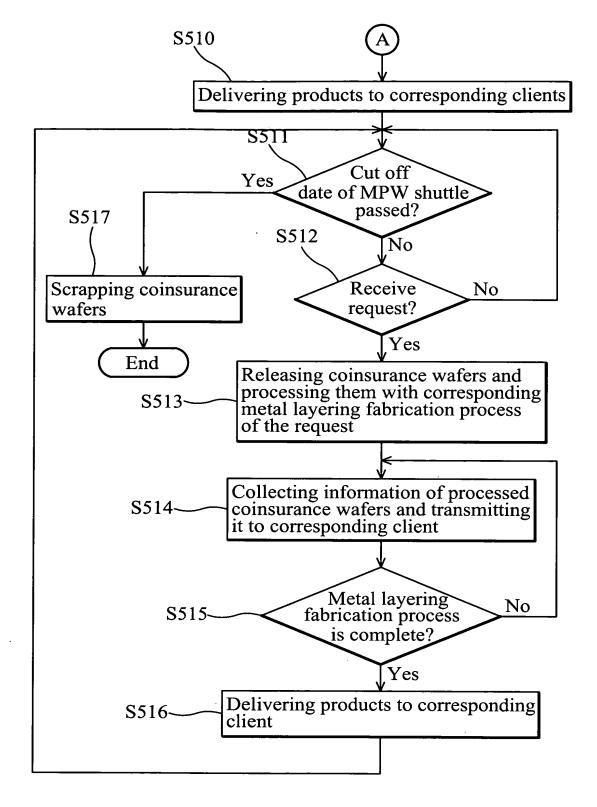


FIG. 5B

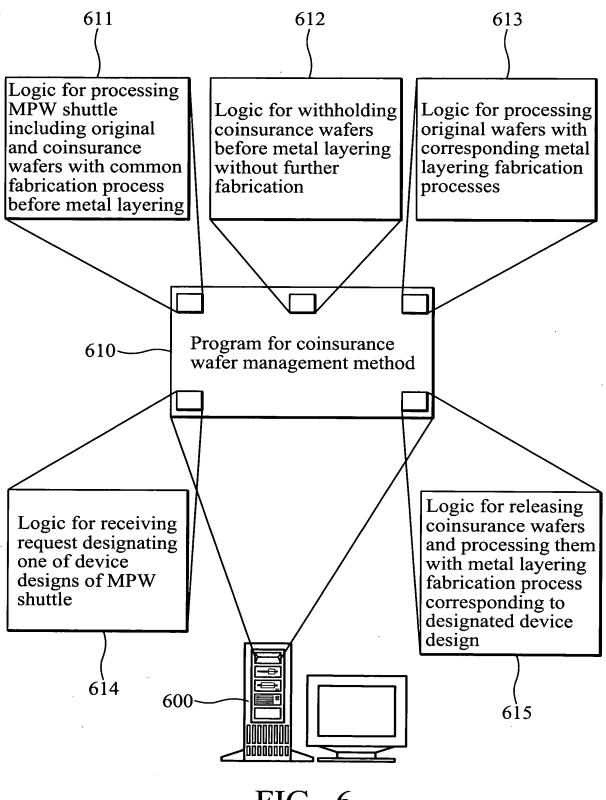


FIG. 6